

The Perfect Fit for Thin Cell Phone Designs Micron's 2-Megapixel, 1/4-Inch CMOS Camera System-on-a-Chip

Features

- An industry first parallel and serial mobile industry processor interface (MIPI) data output
- DigitalClarity® CMOS imaging technology
- Industry-leading 2.2µm pixel technology
- 15 frames per second (fps) at full resolution;
 30 fps in video mode
- Superior low-light performance
- Ultra-low-power, low-cost
- Internal master clock generated by on-chip phase-locked loop (PLL) oscillator
- Integrated image flow processor (IFP)
- Automatic image correction and enhancement, including lens shading correction
- Arbitrary image decimation with anti-aliasing
- Xenon and LED flash support with fast exposure adaptation
- Two-wire serial interface
- Selectable output data format: ITU-R BT.601 (YCbCr), 565RGB, 555RGB, 444RGB, processed bayer, RAW8 and RAW10-bit

Thin Phone? Think Micron.

High resolution; small factor. Micron's new 2-megapixel, 1/4-inch CMOS image sensor is the perfect fit for today's increasingly popular thin phone designs.

The MT9D112 SOC image sensor—developed using Micron's advanced 2.2µm pixel technology and featuring our exclusive low-noise DigitalClarity technology—provides best-in-class image quality while maintaining a small form factor. Micron's MT9D112 is also the industry's first sensor to incorporate mobile industry processor interface (MIPI) standards that support both a parallel and serial interface (CSI-2 and D-PHY)—a significant advancement in enabling simpler camera designs.

The MT9D112 is a fully integrated SOC sensor with additional logic that simplifies the camera module design, related manufacturing processes, system

integration, power management, and component count. As the first sensor to incorporate MIPI standards, it also provides a common platform for design engineers, leading to higher performance, lower development costs, and faster time to market.

Applications

- Cell phones
- PDAs
- PC cameras

Automated, Integrated, Sophisticated Functionality

The MT9D112 camera system features an integrated microcontroller, a sophisticated IFP, and both parallel and serial MIPI data out. It also includes a programmable general purpose I/O module (GPIO), which can be used to control external auto focus (AF), optical zoom, or mechanical shutter.

The microcontroller manages all components of the camera system and sets key operation parameters for the sensor core to optimize the quality of raw image data entering the IFP. The sensor core consists of an active pixel array of 1,616 x 1,216 pixels; programmable timing and control circuitry, including a PLL and external flash support; analog signal chain with automatic offset correction and programmable gain; and two 10-bit analog-to-digital converters (ADCs).

Low power consumption is an important requirement for all components in wireless devices. The MT9D112 has numerous power-conserving features, including an external SHUTDOWN pin, internal soft standby modes, and the ability to individually shut down unused digital blocks. The ultra-low power requirements and superior low-light



performance of this system-on-a-chip (SOC) make it particularly well suited to mobile applications.

The Complete Picture

If your cell phone design requires high resolution and small form factor, Micron has your image sensor

solution. With mobile imagers ranging from 1.3 to 5 megapixels, you're sure to find one that provides the resolution, form factor, features, and functionality you're looking for and that your customers expect in their high-performance mobile applications. To order, call us at 208-368-3900 or visit us on the Web at www.micron.com/imaging.

Specifications

• **Pixel Size**: 2.2μm x 2.2μm

Array Format (Active):

1,600H x 1,200V

• Imaging Area: 3.55mm x 2.68mm

• Optical Format: 1/4 inch (4:3)

Color Filter

Array: RGB Bayer pattern

• Frame Rates: 15 fps (full resolution)

24 fps (preview mode) 30 fps (video mode)

• MAX Data Rate: 80 megapixels per second

@ 80 MHz

• Master Clock: 6 MHz to 80 MHz

ADC: 10 bit, on-chip

Dynamic Range: 59.5dB

Signal-to-Noise

Ratio: 37.7dB (MAX)

• Responsivity: 0.53 V/lux-sec

Supply Analog: 2.5V-3.1VVoltage: Digital: 1.7V-1.95V

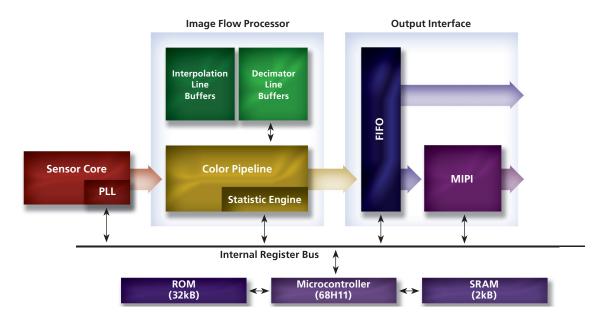
I/O: 1.7V-3.1V PLL: 2.5V-3.1V

• Flash Support: Xenon and LED

• Operating Temp: -30°C to +70°C

Package: Die

SOC Block Diagram



www.micron.com

Products are warranted only to meet Micron's production data sheet specifications. Products and specifications are subject to change without notice.

